



SOLiD WiFi Datasheet

Contents

1.1 Functional description	3
1.1.1. Overview	3
1.1.2. Product features	3
1.1.3. Product description.....	4
1.1.4. Wi-Fi performance	4
1.2 Antenna interfaces	5
1.2.1. External RF antenna interface.....	5
1.3 Pin definition	5
1.4 Electrical specifications.....	6
1.4.1. Absolute maximum ratings	6
1.4.2. Maximum ESD ratings	6
1.4.3. Operating conditions	6
1.4.3.1 Temperature range.....	6
1.4.3.2 Power supply	6

1. SOLiD WiFi

1.1 Functional description

This document provides important procedures and information for installing the BARS.

1.1.1. Overview

The SOLiD WiFi is a high-performance front-end Wi-Fi module with USB and SDIO host interfaces.

This module supports Wi-Fi IEEE 802.11b/g/n.

Comprising an integrated MAC/baseband processor, RF front-end components, and a band-pass filter, SOLiD WiFi complies with IEEE 802.11b/g/n Wi-Fi standards.

The module includes internal one-time programmable (OTP) memory that can store both the radio configuration and the MAC address, and the I/O voltage level can be selected between 1.8 V and 3.3 V.

1.1.2. Product features

Radio	SOLiD WiFi
Wi-Fi IEEE 802.11 standards	b/g/n
Wi-Fi 2.4 / 5 [GHz]	2.4
Channel width [MHz]	20
Antenna type	1a
OS support	
Android / Linux (from u-blox)	•
Interfaces	
SDIO [version]	v2
USB 2.0	1
Features	
Micro Access Point [max connects]	8
AES hardware support	•
Wi-Fi direct	•
Factory-assigned MAC address	•
Factory calibrated RF	•

1a= 1pin for external antenna

1.1.3. Product description

SOLiD WiFi includes an antenna pin for an external antenna and a regular bandpass filter. Used with an external antenna

1.1.4. Wi-Fi performance

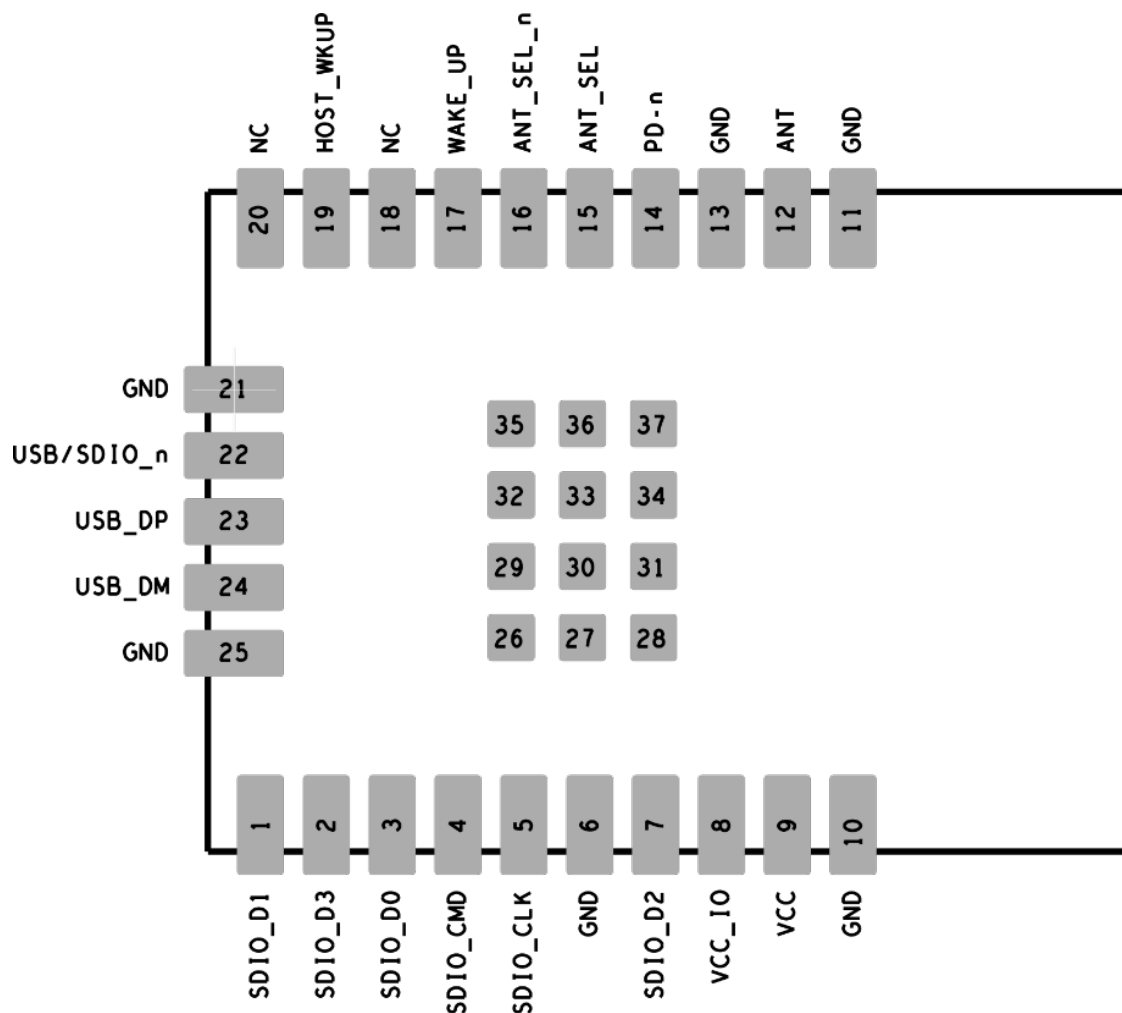
#	Feature	Description
1	Standards	IEEE 802.11b/g/n
2	Frequency bands	2.4 GHz (2412 - 2462 MHz)
3	Channel bandwidth	20 MHz
4	Data rates	802.11b / 1, 2, 5.5 and 11 Mbps 802.11g / 6, 9, 12, 18, 24, 36, 48 and 54 Mbps 802.11n / MCS0-MCS7 (max 72.2Mbps)
5	Hardware supported Encryptions/Decryption	AES/CCMP, AES/CMAC, WAPI, WEP/TKIP
6	Maximum output power	16 dBm (Tolerance: +/- 2dB)
7	Maximum sensitivity	-97 dBm EIRP
8	802.11n features	1-stream STBC reception Short guard interval RIFS on receive path for 802.11n packets Greenfield Tx/Rx
9	Additional IEEE 802.11 support	802.11d international roaming 802.11e quality of service 802.11h transmit power control 802.11i enhanced security 802.11k radio resource measurement*** 802.11n block acknowledgment extension 802.11r fast hand-off for AP roaming*** Fully supports clients (stations) implementing IEEE Wi-Fi direct connectivity

1.2 Antenna interfaces

1.2.1. External RF antenna interface

SOLiD WiFi has an antenna signal (ANT) pin with a characteristic impedance of 50 Ω for using an external antenna. The antenna signal supports both Tx and Rx

1.3 Pin definition



1.4 Electrical specifications

Stressing the device above one or more of the Absolute maximum ratings can cause permanent damage. These are stress ratings only. Operating the module at these or at any conditions other than those specified in the Operating conditions should be avoided. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

1.4.1. Absolute maximum ratings

Symbol	Description	Condition	Min	Max	Unit
VCC	Module supply voltage	Input DC voltage at VCC pin	-	4.0	V
VCC_IO	IO voltage supply	Input DC voltage at VCC_IO pin	1.8 V mode	2.2	V
			3.3 V mode	4.0	V

1.4.2. Maximum ESD ratings

Applicability				Immunity level	Unit
All pins except ANT	Human Body Model (HBM), ANSA/ESDA/JEDEC JS-001-2014.			±2000	V
	Charged Device Model (CDM), JESD22-C101.			±500	V
ANT pin and Internal antenna	Human Body Model (HBM), ANSA/ESDA/JEDEC JS-001-2014.			±300	V
	Charged Device Model (CDM), JESD22-C101.			±600	V

1.4.3. Operating conditions

1.4.3.1 Temperature range

Parameter	Min	Max	Unit
Storage temperature	-40	+85	°C
Operating temperature	-40	+85	°C

1.4.3.2 Power supply

Symbol	Parameter	Min.	Typ.	Max.	Unit
VCC	Supply voltage	3.00	3.30	3.60	V
VCC_IO	Digital IO supply voltage	1.8 V mode	1.80	1.98	V
		3.3 V mode	3.00	3.30	V

1.5 Antennas

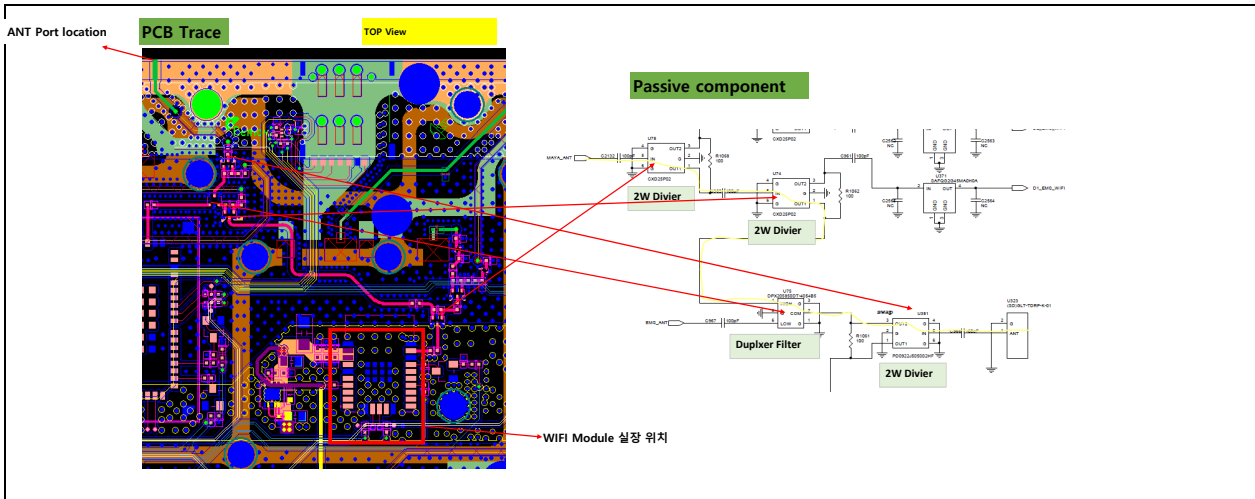
The antenna/trace antenna is installed in the host device (SOLiD BARS HE) and can be operated within it. The trace antenna is integrated into the HE board, and if the trace shown below is not used, testing and submission must be performed in accordance with the C2PC procedure.

1.5.1. Approved antennas

Wi-Fi external antenna, PN YECT002AA	
Manufacturer	QUECTEL
Polarization	Vertical
Gain	+2.9 dBi
Impedance	50 Ω
Size	196.2 × 16 × 13 mm
Type	Omni-directional
Connector	Reverse SMA Male (Antenna Connector (SMA, Male) + Reverse SMA Adaptor (SMA Female – Reverse SMA Male))
Comment	The adapter and antenna connector are permanently bonded and cannot be disassembled without causing damage. This ensures that end users cannot remove or replace the connector, maintaining compliance with the certified configuration
Approval	FCC



Antenna Trace Design



PCB Dielectric constant: 4.4
Impedance: 50 Ohm

PCB Stack up

[2.0 T - 16 L] - Impedance - 50,90,100 Ohm Stack-up

Startup Coordination					Single - 50 Ohm												Differential - 50 Ohm												Differential - 100 Ohm												Differential - 50 Ohm (CPWG)												Single - RF 50 Ohm											
Based On Flow Information					DE_Espected Value				DE_Espected Value				DE_Espected Value				DE_Espected Value				DE_Espected Value				DE_Espected Value				DE_Espected Value				DE_Espected Value				DE_Espected Value																											
Layer #	Type	Diagram or Layer Sequence			Glass Type	Predicted Time (min)	Simulated Time (min)	Time (min)	Space (mm)	Simulated Space (mm)	Time (min)	Space (mm)	Simulated Time (min)	Time (min)	Space (mm)	Simulated Time (min)	Time (min)	Space (mm)	Simulated Time (min)	Time (min)	Space (mm)	Simulated Time (min)	Time (min)	Space (mm)	Simulated Time (min)	Time (min)	Space (mm)	Simulated Time (min)	Time (min)	Space (mm)	Simulated Time (min)																																	
		Plating	Plating		Plating	0.001	0.001	0.00	90 ±10%					0.075	0.22	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
1	Copper Foil	Pre-preg	layer 1	TOP	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
2	Copper Foil	Pre-preg	layer 2	GND	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
3	Copper Foil	Pre-preg	layer 3	Signal	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
4	Copper Foil	Pre-preg	layer 4	GND	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
5	Copper Foil	Pre-preg	layer 5	Signal	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
6	Copper Foil	Pre-preg	layer 6	GND+SIG	GND+SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
7	Copper Foil	Pre-preg	layer 7	GND+SIG	GND+SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
8	Copper Foil	Pre-preg	layer 8	VCC2	VCC2	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
9	Copper Foil	Pre-preg	layer 9	VCC3	VCC3	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
10	Copper Foil	Pre-preg	layer 10	Signal	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.12	0.2	0.3	100 ±10%	0.105	0.3	90 ±10%																																									
11	Copper Foil	Pre-preg	layer 11	GND	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%	0.08	0.3	90 ±10%																																									
12	Copper Foil	Pre-preg	layer 12	Signal	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
13	Copper Foil	Pre-preg	layer 13	GND	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
14	Copper Foil	Pre-preg	layer 14	Signal	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.22	0.3	89 ±10%																																												
15	Copper Foil	Pre-preg	layer 15	GND	GND	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
16	Copper Foil	Pre-preg	layer 16	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
17	Copper Foil	Pre-preg	layer 17	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
18	Copper Foil	Pre-preg	layer 18	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
19	Copper Foil	Pre-preg	layer 19	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
20	Copper Foil	Pre-preg	layer 20	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
21	Copper Foil	Pre-preg	layer 21	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
22	Copper Foil	Pre-preg	layer 22	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
23	Copper Foil	Pre-preg	layer 23	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
24	Copper Foil	Pre-preg	layer 24	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
25	Copper Foil	Pre-preg	layer 25	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
26	Copper Foil	Pre-preg	layer 26	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
27	Copper Foil	Pre-preg	layer 27	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
28	Copper Foil	Pre-preg	layer 28	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
29	Copper Foil	Pre-preg	layer 29	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
30	Copper Foil	Pre-preg	layer 30	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
31	Copper Foil	Pre-preg	layer 31	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
32	Copper Foil	Pre-preg	layer 32	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
33	Copper Foil	Pre-preg	layer 33	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
34	Copper Foil	Pre-preg	layer 34	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
35	Copper Foil	Pre-preg	layer 35	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
36	Copper Foil	Pre-preg	layer 36	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
37	Copper Foil	Pre-preg	layer 37	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
38	Copper Foil	Pre-preg	layer 38	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
39	Copper Foil	Pre-preg	layer 39	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
40	Copper Foil	Pre-preg	layer 40	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
41	Copper Foil	Pre-preg	layer 41	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
42	Copper Foil	Pre-preg	layer 42	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
43	Copper Foil	Pre-preg	layer 43	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
44	Copper Foil	Pre-preg	layer 44	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
45	Copper Foil	Pre-preg	layer 45	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
46	Copper Foil	Pre-preg	layer 46	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
47	Copper Foil	Pre-preg	layer 47	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
48	Copper Foil	Pre-preg	layer 48	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
49	Copper Foil	Pre-preg	layer 49	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
50	Copper Foil	Pre-preg	layer 50	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
51	Copper Foil	Pre-preg	layer 51	SIG	SIG	0.001	0.001	0.00	90 ±10%					0.075	0.2	100 ±10%	0.1	0.24	0.3	90 ±10%	0.45	0.4	90 ±10%																																									
52	Copper Foil	Pre-preg	layer 52	SIG	SIG	0.001	0.001																																																									

Top Trace 폭: 0.45mm

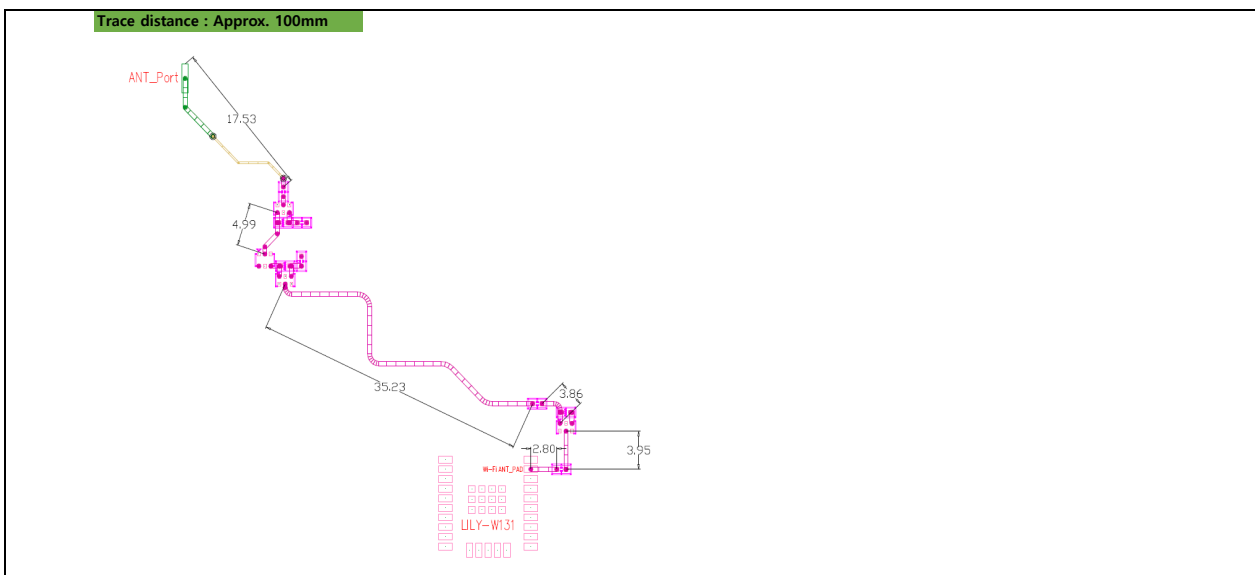
두께 0.3oz(0.0108mm)

Inner Trace 폭: 0.18mm

두께 0.5oz(0.018mm)

Bottom Trace 폭: 0.45mm

두께 0.3oz(0.0108mm)



Passive Component

Component	Part name	Q'TY	LOCATION
2way-divider	CXD25P02	2	U74, U78
2way-divider	DPX205850DT-4054B5	1	U75
Diplexer	PD0922J505032HF	1	U381
CHIP CAPACITORS	100pF/1005/50V/±5%, / C105C101J85NNNC	3	C965, C966, C2132
CHIP RESISTOR	100. 5%/1005/ WR04X101JTL	3	R1061, R1062, R1068

1. Test procedures for design verification.

RF Performance Test
Objective
-Verify the designed frequency band and output performance. -Confirm that the module operates within the normal output range.
Procedure
1. Test Equipment Preparation
-Spectrum analyzer or power meter -Test antenna or RF cable (50 Ω) -Test environment: Anechoic chamber or shield box
2. Transmit Output Power (Tx Power) Measurement
- Configure the module in test mode (Tx continuous mode) - Measure transmit power at low, mid, and high channels - Compare the measured values with datasheet specifications
3. Module Normal Output Verification
- Ensure the measured output is within the designed range Tolerance : ± 5 dB
4. Record Test Results
- Document measurement results for each channel - Mark pass/fail and note any special observations

2. Production test procedures are used to ensure compliance.

RF Performance Test
Objective
-Verify the designed frequency band and output performance. -Confirm that the module operates within the normal output range.
Procedure
1. Test Equipment Preparation
-Spectrum analyzer or power meter -Test antenna or RF cable (50 Ω) -Test environment: Anechoic chamber or shield box
2. Transmit Output Power (Tx Power) Measurement
- Configure the module in test mode (Tx continuous mode) - Measure transmit power at low, mid, and high channels - Compare the measured values with datasheet specifications
3. Module Normal Output Verification
- Ensure the measured output is within the designed range Tolerance : ± 5 dB
4. Record Test Results
- Mark pass/fail

1.6 FCC Statements

FCC Part 15.19 Statements:

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

FCC Part 15.21 statement

Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

FCC Part 15.105 statement

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

1. This device may not cause harmful interference, and
2. This device must accept any interference received, including interference that may cause undesired operation.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that the interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna
- Increase the separation between the equipment and receiver
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.

Consult the dealer or an experienced radio/TV technician for help.

Regulatory notice to host manufacturer according to <KDB 996369 D03 OEM Manual v01>

List of applicable FCC rules

This module has been granted modular approval as below listed FCC rule parts.

-FCC Rule parts 15.247

Summarize the specific operational use conditions

-The OEM integrator should use equivalent antennas which is the same type and equal or less gain than an antenna listed below in this instruction manual.

Limited module procedures (Only limited modular approval)

Single module

Trace antenna designs (Only trace antenna module) (Refer to the Page.7 in this Manual)

If trace antenna designs are applicable, full-detail design specifications are required per D02 Module Q&A Question 11.

For a modular transmitter with trace antenna designs, see the guidance in Question 11 of KDB Publication 996369 D02 FAQ – Modules for Micro-Strip Antennas and traces. The integration information shall include for the TCB review the integration instructions for the following aspects: layout of trace design, part list (BOM), antenna, connectors, and isolation requirements.

- a) Information that includes permitted variances(e.g., trace boundary limits, thickness, length, width, shape(s), dielectric constant, and impedance as applicable for each type of antenna);
- b) Each design shall be considered a different type (e.g., antenna length in multiple(s) of frequency, the wavelength, and antenna shape (traces in phase) can affect antenna gain and must be considered);
- c) The parameters shall be provided in a manner permitting host manufacturers to design the printed circuit (PC) board layout;
- d) Appropriate parts by manufacturer and specifications;
- e) Test procedures for design verification; and
- f) Production test procedures for ensuring compliance

RF exposure considerations

The module has been certified for integration into products only by OEM integrators under the following condition:

- The antenna(s) must be installed such that a minimum separation distance of at least **20 cm** is maintained between the radiator (antenna) and all persons at all times.
- The transmitter module must not be co-located or operating in conjunction with any other antenna or transmitter except in accordance with FCC multi-transmitter product procedures.

Antennas

This module is certified with the following integrated antenna.

-Type: Omni-directional

1) Ant (Wi-Fi) Peak gain: 2.9 dBi (Free space)

Any new antenna type, higher gain than listed antennas should be met the requirements of FCC rule 15.203 and 2.1043 as permissive change procedure.

Label and compliance information

End Product Labeling (FCC)

The module is labeled with its own FCC ID. If the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. In that case, the final end product must be labeled in a visible area with the following:

“Contains FCC ID: W6UWIFI

Information on test modes and additional testing requirements

-OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed (for example, digital device emissions, PC peripheral

requirements, additional transmitter in the host, etc.).

Additional testing, Part 15 Subpart B disclaimer

-The final host product also requires Part 15 subpart B compliance testing with the modular transmitter installed to be properly authorized for operation as a Part 15 digital device.

Note EMI Considerations

Note that a host manufacture is recommended to use D04 Module Integration Guide recommending as "best practice" RF design engineering testing and evaluation in case non-linear interactions generate additional non-compliant limits due to module placement to host components or properties

For standalone mode, reference the guidance in D04 Module Integration Guide and for simultaneous mode; see D02 Module Q&A Question 12, which permits the host manufacturer to confirm compliance.

How to make changes

Since only Grantees are permitted to make permissive changes, when the module will be used differently than granted, please contact the module manufacture on below contact information.

-. Contact information: yckim@solid.co.kr / Tel: +82-31-627-6292